



Click [here](#) for the 3D model.

Dimensions	
Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	0.78mm +/-0.10mm
B	0.5mm +/-0.25mm

  

Packaging Specifications	
Packaging	Cut Reel
Packaging Quantity	500

General Information	
Series	SMD Indust COG HT200C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Low Loss
Features	High Temp, Ultra-Stable, Low Loss
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.027 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	37.037 GOhms